



STFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Tien-J Bao, et al.	§	Docket No.:	TS02-262CIP
		§		(24061.480)
Serial No.:	10/808,801	§	Customer No.	42717
		§		
Filing Date:	March 25, 2004	§	Art Unit:	2891
		§		
For:	Method for Forming Openings	§	Examiner:	Anya, Igwe U.
	in Low-K Dielectric Layers	§	Conf. No.:	6033
		§		

RESPONSE

Commissioner For Patents
PO Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the non-final Office Action mailed June 3, 2005, please reconsider the application in light of the following amendments and remarks:

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 7 of this paper.